TRUTH TABLE

	Outputs		
OE	LE	D _n	O _n
L	Н	Н	Н
L	Н	L	L
L	L	Х	O ₀
Н	Х	Х	Z

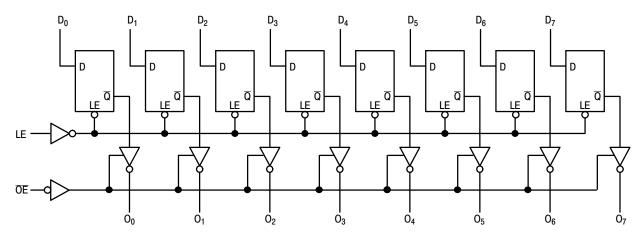
H = HIGH Voltage Level L = LOW Voltage Level Z = High Impedance

X = Immaterial

O₀ = Previous O₀ before LOW-to-HIGH Transition of Clock

Functional Description

The MC74AC573/74ACT574 contains eight D–type latches with 3–state output buffers. When the Latch Enable (LE) input is HIGH, data on the D_n inputs enters the latches. In this condition the latches are transparent, i.e., a latch output will change state each time its D input changes. When LE is LOW the latches store the information that was present on the D inputs a setup time preceding the HIGH–to–LOW transition of LE. The 3–state buffers are controlled by the Output Enable (\overline{OE}) input. When \overline{OE} is LOW, the buffers are enabled. When \overline{OE} is HIGH the buffers are in the high impedance mode but this does not interfere with entering new data into the latches.



NOTE: That this diagram is provided only for the understanding of logic operations and should not be used to estimate propagation delays.

Figure 3. Logic Diagram

MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V _{CC}	DC Supply Voltage (Referenced to GND)	-0.5 to +7.0	V
V _{IN}	DC Input Voltage (Referenced to GND)	-0.5 to V _{CC} +0.5	V
V _{OUT}	DC Output Voltage (Referenced to GND) (Note 1)	-0.5 to V _{CC} +0.5	V
I _{IK}	DC Input Diode Current	±20	mA
I _{OK}	DC Output Diode Current	±50	mA
I _{OUT}	DC Output Sink/Source Current	±50	mA
I _{CC}	DC Supply Current, per Output Pin	±50	mA
I _{GND}	DC Ground Current, per Output Pin	±100	mA
T _{STG}	Storage Temperature Range	-65 to +150	°C
TL	Lead temperature, 1 mm from Case for 10 Seconds	260	°C
T_J	Junction Temperature Under Bias	140	°C
$\theta_{\sf JA}$		OIC 65.8 SOP 110.7	°C/W
MSL	Moisture Sensitivity	Level 1	
F _R	Flammability Rating Oxygen Index: 30% – 3	35% UL 94 V–0 @ 0.125 in	
V _{ESD}	ESD Withstand Voltage Human Body Model (Not Machine Model (Not Charged Device Model (Not Charge	e 4) > 200	V
I _{Latchup}	Latchup Performance Above V _{CC} and Below GND at 85°C (Not	e 6) ±100	mA

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- 1. I_{OUT} absolute maximum rating must be observed.
- The package thermal impedance is calculated in accordance with JESD 51–7.
- 3. Tested to EIA/JESD22-A114-A.
- 4. Tested to EIA/JESD22-A115-A.
- Tested to JESD22-C101-A.
- 6. Tested to EIA/JESD78.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Тур	Max	Unit
V	Complex Voltage	'AC	2.0	5.0	6.0	V
V _{CC}	Supply Voltage	'ACT	4.5	5.0	5.5	V
V _{IN} , V _{OUT}	DC Input Voltage, Output Voltage (Ref. to GND)		0	-	V _{CC}	V
		V _{CC} @ 3.0 V	-	150	-	
t _r , t _f	Input Rise and Fall Time (Note 1) 'AC Devices except Schmitt Inputs	V _{CC} @ 4.5 V	-	40	-	ns/V
		V _{CC} @ 5.5 V	-	25	_	
	Input Rise and Fall Time (Note 2)	V _{CC} @ 4.5 V	-	10	-	no/\/
t _r , t _f	'ACT Devices except Schmitt Inputs	V _{CC} @ 5.5 V	-	8.0	_	ns/V
T _A	Operating Ambient Temperature Range		-40	25	85	°C
I _{OH}	Output Current – High		-	_	-24	mA
I _{OL}	Output Current – Low		-	_	24	mA

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

- V_{IN} from 30% to 70% V_{CC}; see individual Data Sheets for devices that differ from the typical input rise and fall times.
 V_{IN} from 0.8 V to 2.0 V; see individual Data Sheets for devices that differ from the typical input rise and fall times.

DC CHARACTERISTICS

			74	AC	74AC		
Symbol	Parameter	V _{CC} (V)	T _A = -	+25°C	T _A = -40°C to +85°C	Unit	Conditions
			Тур	Guar	anteed Limits		
V _{IH}	Minimum High Level Input Voltage	3.0 4.5 5.5	1.5 2.25 2.75	2.1 3.15 3.85	2.1 3.15 3.85	V	V _{OUT} = 0.1 V or V _{CC} – 0.1 V
V _{IL}	Maximum Low Level Input Voltage	3.0 4.5 5.5	1.5 2.25 2.75	0.9 1.35 1.65	0.9 1.35 1.65	V	V _{OUT} = 0.1 V or V _{CC} – 0.1 V
V _{OH}	Minimum High Level Output Voltage	3.0 4.5 5.5	2.99 4.49 5.49	2.9 4.4 5.4	2.9 4.4 5.4	V	I _{OUT} = -50 μA
		3.0 4.5 5.5	- - -	2.56 3.86 4.86	2.46 3.76 4.76	V	* V _{IN} = V _{IL} or V _{IH} -12 mA I_{OH} -24 mA -24 mA
V _{OL}	Maximum Low Level Output Voltage	3.0 4.5 5.5	0.002 0.001 0.001	0.1 0.1 0.1	0.1 0.1 0.1	V	Ι _{ΟυΤ} = 50 μΑ
		3.0 4.5 5.5	- - -	0.36 0.36 0.36	0.44 0.44 0.44	V	* V _{IN} = V _{IL} or V _{IH} 12 mA I _{OL} 24 mA 24 mA
I _{IN}	Maximum Input Leakage Current	5.5	-	±0.1	±1.0	μΑ	$V_I = V_{CC}$, GND
I _{OZ}	Maximum 3-State Current	5.5	-	±0.5	±5.0	μΑ	V_{I} (OE) = V_{IL} , V_{IH} V_{I} = V_{CC} , GND V_{O} = V_{CC} , GND
I _{OLD}	†Minimum Dynamic	5.5	-	_	75	mA	V _{OLD} = 1.65 V Max
I _{OHD}	Output Current	5.5	-	_	-75	mA	V _{OHD} = 3.85 V Min
Icc	Maximum Quiescent Supply Current	5.5	-	8.0	80	μΑ	V _{IN} = V _{CC} or GND

NOTE: I_{IN} and $I_{CC} @ 3.0 \text{ V}$ are guaranteed to be less than or equal to the respective limit @ 5.5 V V_{CC} . *All outputs loaded; thresholds on input associated with output under test. †Maximum test duration 2.0 ms, one output loaded at a time.

AC CHARACTERISTICS (For Figures and Waveforms – See Section 3)

				74AC		74	AC		
Symbol	Parameter	V _{CC} * (V)	V_{CC}^* $T_A = +25^{\circ}C$ $C_L = 50 \text{ pF}$		C F	$T_A = -40^{\circ}C$ to +85°C $C_L = 50 \text{ pF}$		Unit	Fig. No.
			Min	Тур	Max	Min	Max		
t _{PLH}	Propagation Delay D _n to O _n	3.3 5.0	2.5 2.5		13.0 10.0	2.0 2.0	15.0 11.5	ns	3–5
t _{PHL}	Propagation Delay D _n to O _n	3.3 5.0	2.5 2.5	-	12.0 9.5	2.0 2.0	14.0 11.0	ns	3–5
t _{PLH}	Propagation Delay LE to O _n	3.3 5.0	2.5 2.5	-	13.0 9.5	2.0 2.0	15.0 11.0	ns	3–6
t _{PHL}	Propagation Delay LE to O _n	3.3 5.0	2.5 2.5		12.0 8.5	2.0 2.0	14.0 10.0	ns	3–6
t _{PZH}	Output Enable Time	3.3 5.0	2.5 2.5	-	11.0 9.0	2.0 2.0	12.0 10.0	ns	3–7
t _{PZL}	Output Enable Time	3.3 5.0	2.5 2.5	-	11.0 8.5	2.0 2.0	12.5 9.5	ns	3–8
t _{PHZ}	Output Disable Time	3.3 5.0	2.5 2.5	-	12.5 11.0	2.0 2.0	13.5 12.0	ns	3–7
t _{PLZ}	Output Disable Time	3.3 5.0	2.5 2.5	-	9.5 8.0	2.0 2.0	10.5 9.0	ns	3–8

^{*}Voltage Range 3.3 V is 3.3 V ± 0.3 V. Voltage Range 5.0 V is 5.0 V ± 0.5 V.

AC OPERATING REQUIREMENTS

				74AC	74AC		
Symbol	Parameter	V _{CC} * (V)	T _A = +25°C C _L = 50 pF		T _A = -40°C to +85°C C _L = 50 pF	Unit	Fig. No.
			Тур	Guarantee	d Minimum		
t _s	Setup Time, HIGH or LOW D _n to LE	3.3 5.0	-	3.5 3.0	4.0 3.5	ns	3–9
t _h	Hold Time, HIGH or LOW D _n to LE	3.3 5.0	-	2.0 2.0	2.0 2.0	ns	3–9
t _w	LE Pulse Width, HIGH	3.3 5.0	-	6.0 4.0	7.0 5.0	ns	3–6

^{*}Voltage Range 3.3 V is 3.3 V ± 0.3 V. Voltage Range 5.0 V is 5.0 V ± 0.5 V.

DC CHARACTERISTICS

			74 <i>A</i>	CT	74ACT		
Symbol	Parameter	V _{CC} (V)	T _A = +25°C		T _A = -40°C to +85°C	Unit	Conditions
			Тур	Guar	anteed Limits		
V _{IH}	Minimum High Level Input Voltage	4.5 5.5	1.5 1.5	2.0 2.0	2.0 2.0	V	V _{OUT} = 0.1 V or V _{CC} – 0.1 V
V _{IL}	Maximum Low Level Input Voltage	4.5 5.5	1.5 1.5	0.8 0.8	0.8 0.8	V	V _{OUT} = 0.1 V or V _{CC} – 0.1 V
V _{OH}	Minimum High Level Output Voltage	4.5 5.5	4.49 5.49	4.4 5.4	4.4 5.4	V	I _{OUT} = -50 μA
		4.5 5.5	- -	3.86 4.86	3.76 4.76	V	$^*V_{IN} = V_{IL} \text{ or } V_{IH}$ -24 mA I_{OH} -24 mA
V _{OL}	Maximum Low Level Output Voltage	4.5 5.5	0.001 0.001	0.1 0.1	0.1 0.1	V	I _{OUT} = 50 μA
		4.5 5.5		0.36 0.36	0.44 0.44	٧	$^{*}V_{IN} = V_{IL} \text{ or } V_{IH}$ $^{24 \text{ mA}}$ $^{1}OL \qquad 24 \text{ mA}$
I _{IN}	Maximum Input Leakage Current	5.5	_	±0.1	±1.0	μΑ	V _I = V _{CC} , GND
ΔI_{CCT}	Additional Max. I _{CC} /Input	5.5	0.6	_	1.5	mA	$V_{I} = V_{CC} - 2.1 \text{ V}$
I _{OZ}	Maximum 3-State Current	5.5	_	±0.5	±5.0	μΑ	V_{I} (OE) = V_{IL} , V_{IH} V_{I} = V_{CC} , GND V_{O} = V_{CC} , GND
I _{OLD}	†Minimum Dynamic	5.5	-	-	75	mA	V _{OLD} = 1.65 V Max
I _{OHD}	Output Current	5.5	-	_	-75	mA	V _{OHD} = 3.85 V Min
I _{CC}	Maximum Quiescent Supply Current	5.5	_	8.0	80	μΑ	V _{IN} = V _{CC} or GND

 $^{^\}star\text{All}$ outputs loaded; thresholds on input associated with output under test. †Maximum test duration 2.0 ms, one output loaded at a time.

AC CHARACTERISTICS (For Figures and Waveforms – See Section 3)

				74ACT		74	CT		
Symbol	Parameter	V _{CC} *			T _A = -40°C to +85°C C _L = 50 pF		Unit	Fig. No.	
			Min	Тур	Max	Min	Max		
t _{PLH}	Propagation Delay D _n to O _n	5.0	2.5	_	10.5	2.0	12	ns	3–5
t _{PHL}	Propagation Delay D _n to O _n	5.0	2.5	-	10.5	2.0	12	ns	3–5
t _{PLH}	Propagation Delay LE to O _n	5.0	3.0	-	10.5	2.5	12	ns	3–6
t _{PHL}	Propagation Delay LE to O _n	5.0	2.5	-	9.5	2.0	10.5	ns	3–6
t _{PZH}	Output Enable Time	5.0	2.0	-	10	1.5	11	ns	3–7
t _{PZL}	Output Enable Time	5.0	1.5	_	9.5	1.5	10.5	ns	3–8
t _{PHZ}	Output Disable Time	5.0	2.5	-	11	1.5	12.5	ns	3–7
t _{PLZ}	Output Disable Time	5.0	1.5	-	8.5	1.0	9.5	ns	3–8

^{*}Voltage Range 5.0 V is 5.0 V \pm 0.5 V.

AC OPERATING REQUIREMENTS

				74ACT	74ACT		
Symbol	Parameter	V _{CC} * (V)	* T _A = +25°C C _L = 50 pF		T _A = -40°C to +85°C C _L = 50 pF	Unit	Fig. No.
			Тур	Guarantee	d Minimum		
t _S	Setup Time, HIGH or LOW D _n to LE	5.0	-	3.0	3.5	ns	3–9
t _h	Hold Time, HIGH or LOW D _n to LE	5.0	1	0	0	ns	3–9
t _w	LE Pulse Width, HIGH	5.0	-	3.5	4.0	ns	3–6

^{*}Voltage Range 5.0 V is 5.0 V ± 0.5 V.

CAPACITANCE

Symbol	Parameter	Value Typ	Unit	Test Conditions
C _{IN}	Input Capacitance	5.0	pF	V _{CC} = 5.0 V
C _{PD}	Power Dissipation Capacitance	25	pF	V _{CC} = 5.0 V

ORDERING INFORMATION

Device	Package	Shipping [†]
MC74AC573DWG	SOIC-20 (Pb-Free)	38 Units / Rail
MC74AC573DWR2G	SOIC-20 (Pb-Free)	1000 Units / Tape & Reel
MC74AC573DTR2G	TSSOP-20 (Pb-Free)	2500 Units / Tape & Reel
MC74ACT573DWG	SOIC-20 (Pb-Free)	38 Units / Rail
MC74ACT573DWR2G	SOIC-20 (Pb-Free)	1000 Units / Tape & Reel
MC74ACT573DTR2G	TSSOP-20 (Pb-Free)	2500 Units / Tape & Reel

[†]For information on tape and reel specifications,including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

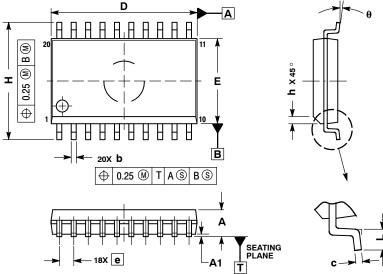




SOIC-20 WB CASE 751D-05 **ISSUE H**

DATE 22 APR 2015

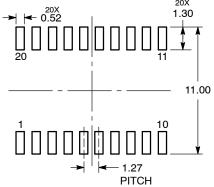
SCALE 1:1



- DIMENSIONS ARE IN MILLIMETERS.
 INTERPRET DIMENSIONS AND TOLERANCES.
- PER ASME Y14.5M, 1994.
 3. DIMENSIONS D AND E DO NOT INCLUDE MOLD
- PROTRUSION.
 MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.
- DIMENSION B DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF B DIMENSION AT MAXIMUM MATERIAL

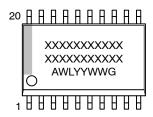
	MILLIN	IETERS
DIM	MIN	MAX
Α	2.35	2.65
A1	0.10	0.25
b	0.35	0.49
С	0.23	0.32
D	12.65	12.95
E	7.40	7.60
е	1.27	BSC
Н	10.05	10.55
h	0.25	0.75
L	0.50	0.90
A	0 °	7 °

RECOMMENDED SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

GENERIC MARKING DIAGRAM*



XXXXX = Specific Device Code = Assembly Location

WL = Wafer Lot ΥY = Year WW = Work Week = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present.

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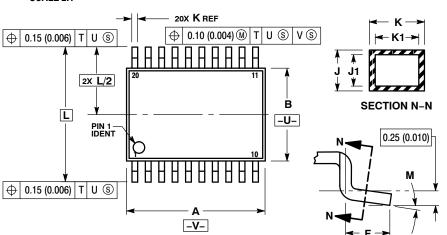
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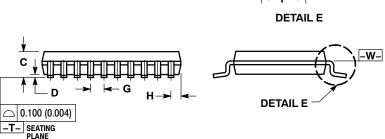
^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.



TSSOP-20 WB CASE 948E ISSUE D

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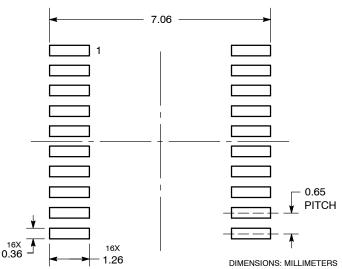
NOTES:

- DIMENSIONING AND TOLERANCING PER
- ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
- 3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.
- FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K
- (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
- TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.

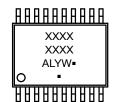
 7. DIMENSION A AND B ARE TO BE
- DETERMINED AT DATUM PLANE -W-

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
Α	6.40	6.60	0.252	0.260
В	4.30	4.50	0.169	0.177
С		1.20		0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
Н	0.27	0.37	0.011	0.015
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0°	8°	0°	8°

SOLDERING FOOTPRINT



GENERIC MARKING DIAGRAM*



= Assembly Location

= Wafer Lot

= Year

= Work Week

= Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present.

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MC74ACT573DTR2G MC74ACT573DW MC74ACT573DWG MC74ACT573DWR2 MC74ACT573DWR2G

MC74ACT573N MC74ACT573NG